

TAS5753MD Evaluation Module

This user's guide describes the operation of the TAS5753MD evaluation module (EVM). The EVM is connected to the PurePath™ Console Motherboard (PPCMB) and is configured using PurePath Console 3 (PPC3) software. Visit the [e2e Audio Amplifiers](#) forum for questions and other support issues.

The main contents of this document are:

- Details for properly connecting a TAS5753MD evaluation module (EVM) and the details of the EVM
- Start-up procedure using PurePath Console 3 (PPC3) software with the correct plugin for the EVM
- Quick-start guide for the common modes in which the TAS5753MDEV is used

Throughout this document, the abbreviation EVM and the term evaluation module are synonymous with the TAS5753MDEV evaluation module, unless otherwise noted.

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1 Overview

The TAS5753MD evaluation module showcases the latest TI digital input Class-D open-loop amplifiers. The TAS5753MD is an I²S input Class-D amplifier with audio processing features and integrated headphone/line driver.

The EVM is configured in *Two-Device 2.1* mode with one stereo device using bridge tied load for left and right channels and one mono device configured for mono applications, such as higher power full-range speakers or subwoofers. The device operating in stereo mode has the headphone/line driver option available via a 3.5-mm plug connector. The EVM is used in conjunction with the PurePath Console Motherboard (PPCMB). The PVDD supply is input on the EVM daughter card, which passes it to the PPCMB motherboard through the J4 connector. Regulators on the PPCMB create the 3.3-V power supply, which is sent back to the DUT through the J4 connector. The EVM is controlled by PPC3 software.

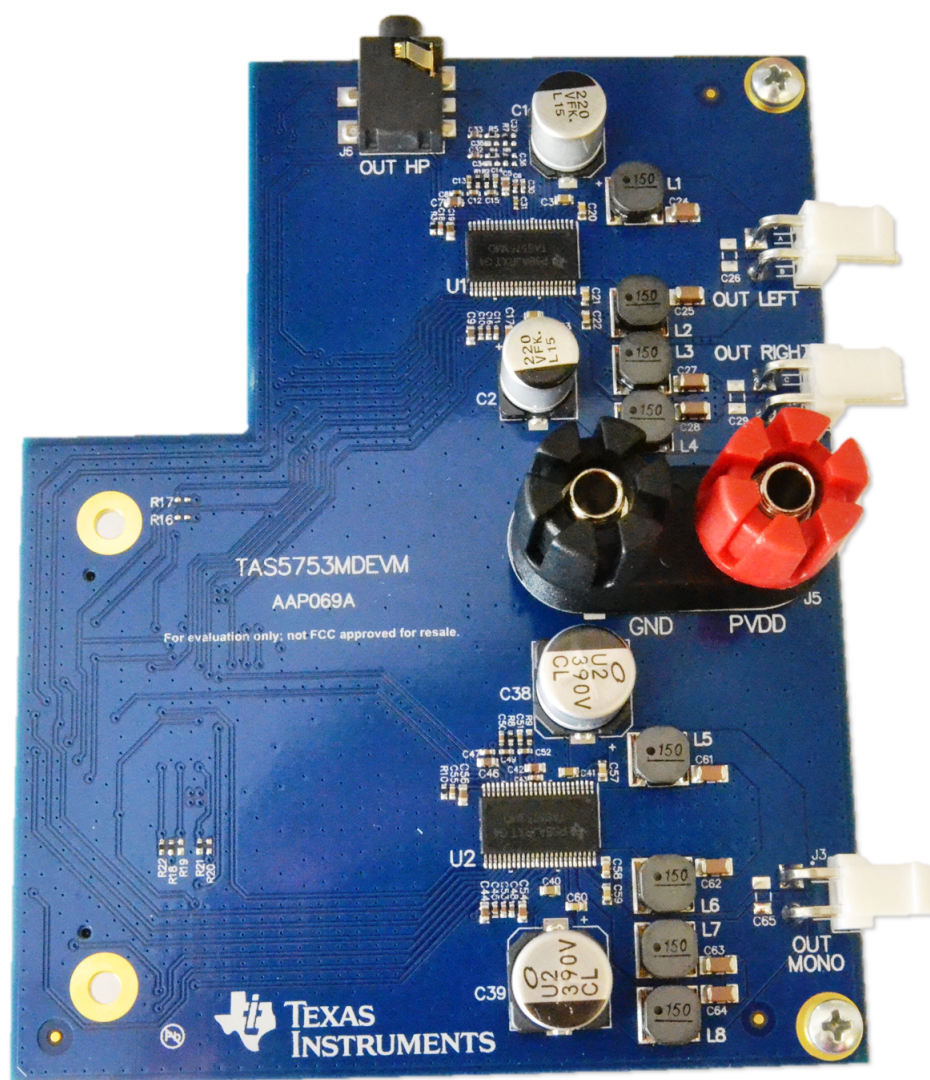


Figure 1. TAS5753MD Evaluation Board

1.1 Features

This EVM supports the following features:

- Control via USB port using TI's PPC3
- Two-Device 2.1 mode, one stereo device and one mono device, both with I²S input from PPCMB
- Analog, optical, coaxial, and USB audio inputs available through PPCMB
- Integrated headphone/line driver amplifier

2 EVM Setup

Figure 2 illustrates the EVM setup.

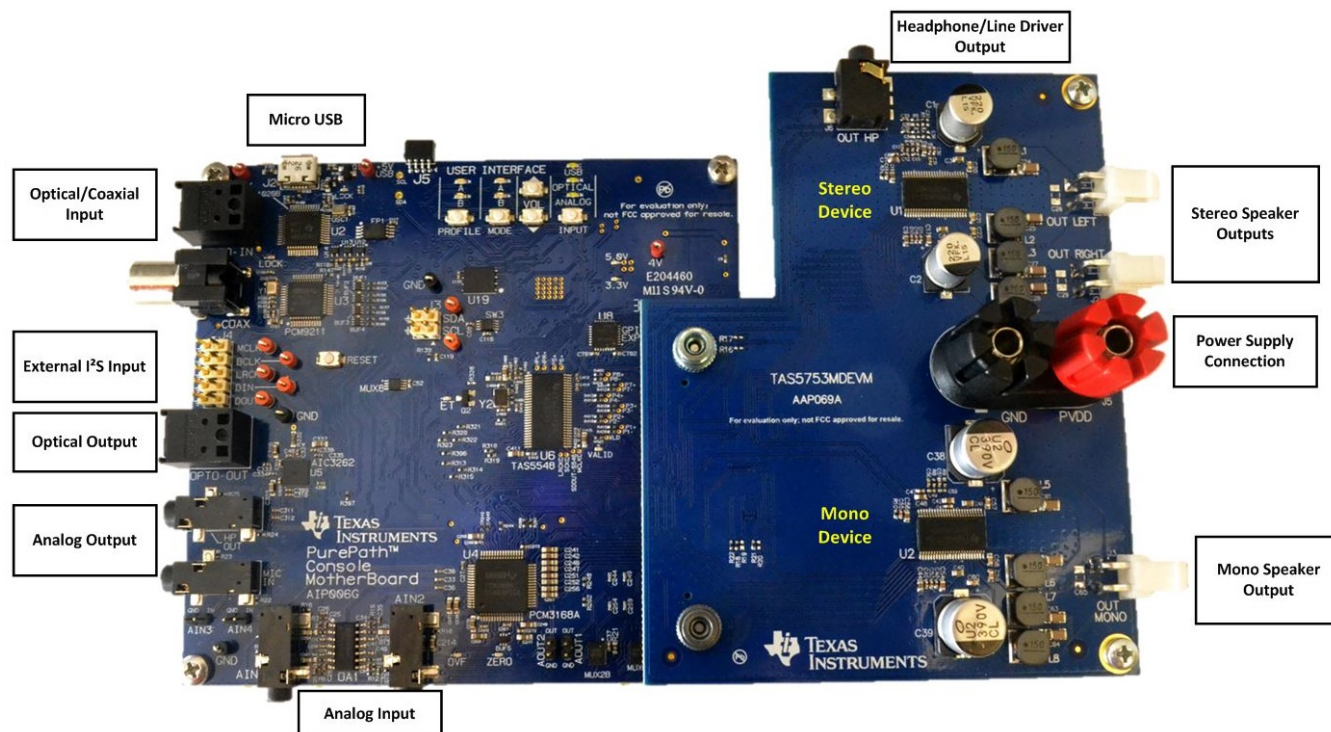


Figure 2. Evaluation Module and PurePath Console Motherboard Connection

2.1 Requirements

The following are required to operate and test this EVM:

- TAS5753MDEVM board
- *PurePath Console* motherboard
- Banana cable, or bare wire lead pair for PVDD/GND connection via five-way binding posts.
- Speaker cable with JST VHR-2N connector
- 2 × 8-Ω speakers for stereo test
- 1 × 4-Ω speakers for mono test
- Power supply (8 V to 26.4 V)
- Audio Source (Analog, USB, Optical)
- Micro type-B USB cable
- *PurePath Console* 3.xx GUI running on a PC

2.2 Software Setup

PurePath Console 3.xx is required to configure the EVM. Download the software from www.ti.com/mysecuresoftware, and install it before connecting the device for the first time.

Prior authorization is required to download the software. Access <http://www.ti.com/tool/purepathconsole> and click the **Request** button to start the approval process. TAS5753MD application for PurePath Console should be requested from the [TAS5753MDEV tool folder](#).

For more information about PurePath Console 3, refer to the *PPC3 User Manual* and *PPC3 Quick Reference Guide* found in www.ti.com/mysecuresoftware.

2.3 Hardware Setup

Use the following steps to setup the hardware:

- Connect the TAS5753MDEV to the PPCMB.
- Connect the power supply to the EVM board and turn on the power. The 5-V and 3.3-V LEDs will become illuminated.
- Connect the micro-USB cable from the PC to the controller board; the USB lock LED will become illuminated.
- Connect an audio source to the PPCMB, this is not necessary if the source is USB audio.
- Connect the speakers to the outputs of the EVM.

3 Using the TAS5753MDEV with PurePath Console 3

3.1 TAS5753MD Application Connection

The TAS5753MD application is available in PPC3 after correct installation and approval. Sign into PPC3 to gain access to the TAS5753MD application installer. After installing, the TAS5753MD application is available.

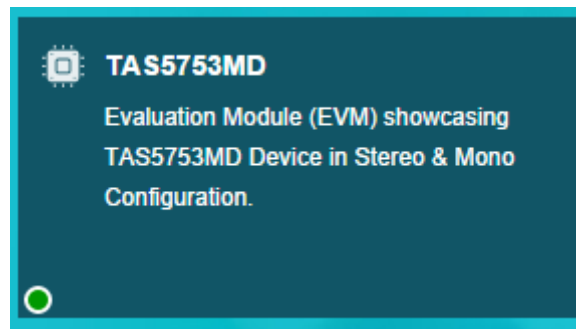


Figure 3. TAS5753MD Application in PurePath Console 3

Verify that the EVM is properly connected to the application by looking in the lower left corner of the TAS5753MD application. A green status circle indicates that the TAS5753MDEV is properly connected to the computer. The device programming is done automatically when opening the application. If the status circle is not green, the EVM may be connected but it is likely not correctly programmed as the TAS5753MDEV. In this case, connection to the EVM must be done manually by clicking on the **Connect** button located on the lower left corner of the window after opening the TAS5753MD application.

When opening the TAS5753MD application, a file window appears offering the option to load a previously saved configuration file, start a new configuration or continue the last session.

3.2 TAS5753MD Application Features

The *Home* window is displayed when the TAS5753MD application is initialized. Several evaluation and integration options are available. TI recommends using the application walkthrough by clicking on the question mark icon available next to the page name in all pages. The application walkthrough feature provides guidance through various sections in the selected page and displays comments explaining the sections of the page. Close the application walkthrough at any time by clicking on the 'x' mark at the top right corner of the pop up. Navigate through the previous and next sections in the page by clicking on the left or right arrows.

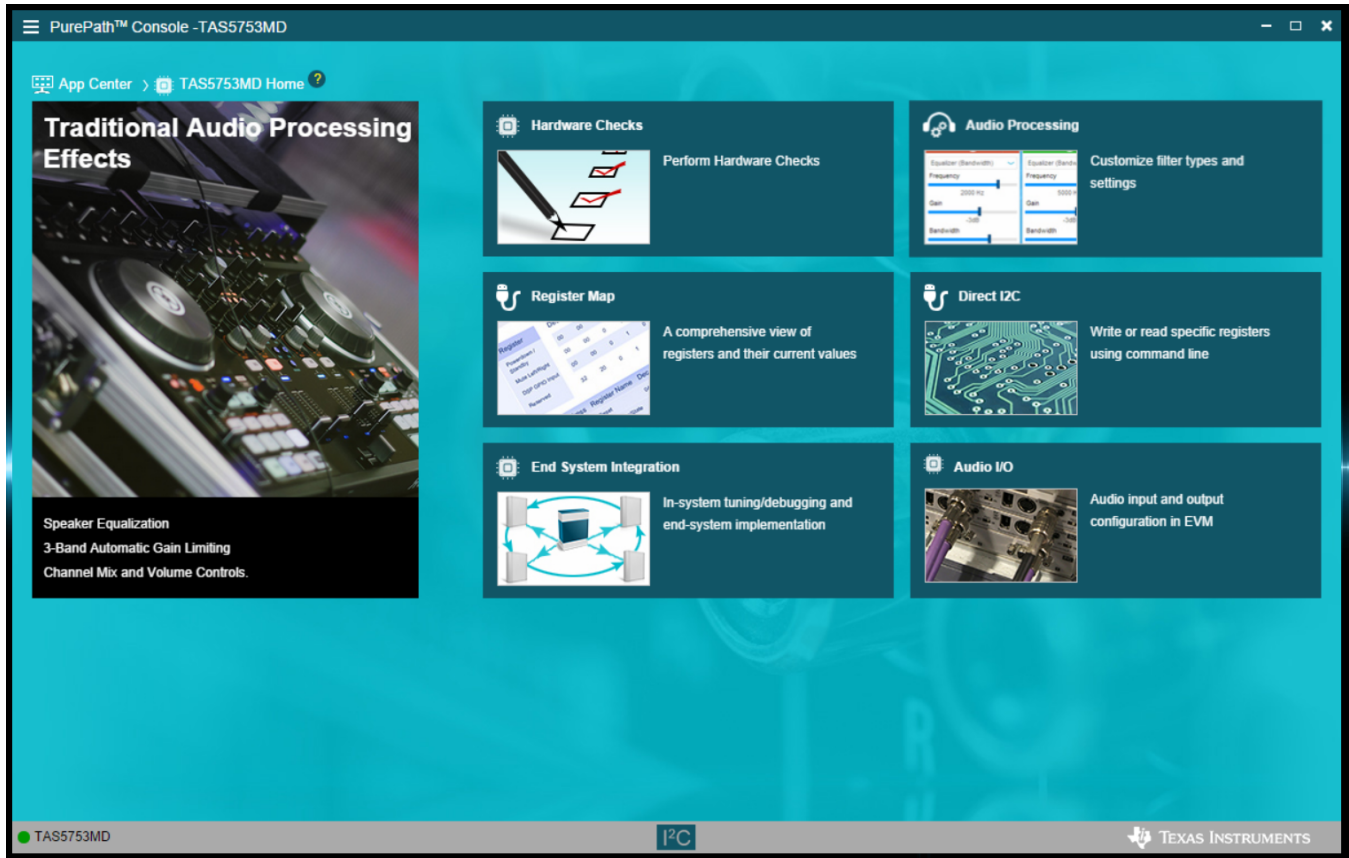
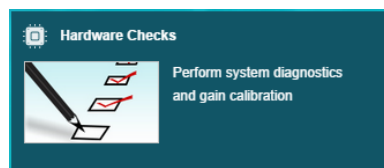


Figure 4. TAS5753MD Application Home Window

3.3 Hardware Checks

The following window verifies the correct connection of the evaluation module, checking if the hardware is correctly configured to test the EVM.



Perform a system calibration before proceeding to the *Tuning and Audio Processing* window. If an attempt to enter the *Tuning and Audio Processing* window is made before performing hardware checks, PPC3 prompts with a window requesting to perform the verification of the hardware. Only new sessions require a hardware check, so this window will not appear when continuing from a previous session or loading a previously saved one.

Ensure that the PurePath Console motherboard and EVM are recognized as USB-AudioEVM, and that the sampling frequency is set to 48 kHz. Otherwise, the hardware check fails and the EVM evaluation may not be correct. This information is found under sound settings in the control panel of the host computer.

3.4 Audio I/O



This tool selects the desired audio input to test the board. USB, optical, coaxial, and line inputs are supported by the motherboard. USB audio source is selected as default but there is an option to enable or disable the audio source to the amplifier by clicking on *Speaker out*. The available sampling rates for each digital input are shown in [Table 1](#).

Table 1. Available Sample Rates for Each Digital Input

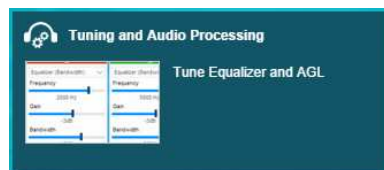
Input	Sampling rates available
USB in	48 kHz
Optical In	48 kHz / 44.1 kHz
Coax In	48 kHz / 44.1 kHz

Although PPCMB operating range is up to 192 kHz, the available sample rates are limited to the TAS5753MD.

The headphone output of the stereo amplifier can be turned on or off in the *Audio I/O* window. The source for the headphone output of the evaluation module is the analog input of the PPCMB.

3.5 Tuning and Audio Processing

The main features of the amplifier audio processing are configured through this window. After opening the *Tuning and Audio Processing* window, the devices in the EVM are configured with default settings. USB audio is selected as the audio source by default. Configuration options include which device on the board (either stereo or mono) is being configured, the audio source for the amplifiers, as well as the audio processing features available in the device. The option to save the changes made during the audio tuning using the snapshot feature of PPC3 is also available.



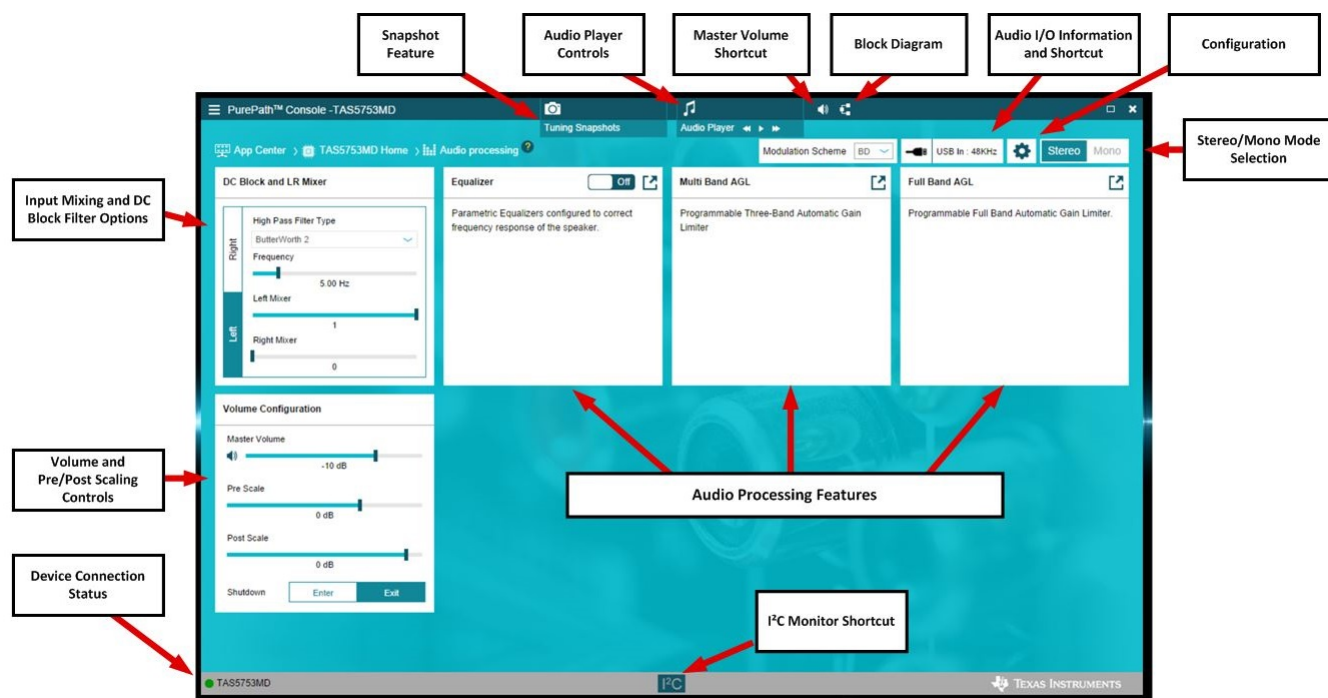


Figure 5. TAS5753MDEVM Audio Processing Windows

Stereo/Mono device selection

Configure each device of the EVM individually by selecting between **Stereo** and **Mono** on the upper right section of the *Audio Processing* window. The configuration of each device is made with the same controls; the only difference is that when configuring the mono device, the channel (left or right) driving the power stage is selected. Detailed information is found in the **Configuration** section.



Configuration

Access the configuration menu by clicking in the gear icon next to the **Stereo/Mono selection** button. In Stereo mode, only the option to reset the tuning done in the GUI is offered, in mono mode, the user can select also if the left or right channel from the digital audio processor drives the power stage of the amplifier. When performing the Reset tuning function, the devices are configured with the default settings. By default, both devices are configured with a master volume gain of -10 dB, multiband AGCs are set to 0 dB while full band AGC is set to -1 dB. Stereo device equalizers are turned off, but mono device has a default-configured 120-Hz low-pass filter for use in subwoofer applications. The left channel of the mono device is driving the power stage by default.



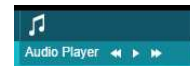
Audio I/O shortcut

This section shows the audio source and sampling frequency that is used to generate the I²S input for the TAS5753MD amplifiers. The user is redirected to the main Audio I/O window after clicking this button.



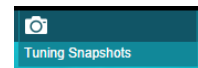
Audio Player

The Audio Player is used to play audio tracks available in the PC and perform various tuning operations. Clicking on the Audio Player launches a floating window, where audio tracks are added or played.



Tuning Snapshots

Tuning Snapshot stores all the values of the current setting. A maximum of 5 Snapshots can be stored. When clicking on Tuning Snapshots, the Tuning History Navigator is opened. Tuning History Navigator saves the history of the tuning changes with each node corresponding to a single tune setting changed from the previous node. More information about Tuning History Navigator and Tuning Snapshots is found in the PPC3 User Manual.



I²C Monitor

Use the *I²C Monitor* to execute direct read and write commands to the device and view the I²C transactions happening as a result of device operation performed using the PPC3 application. *I²C Monitor* has the same functionality of the Direct I²C tool available in the *Home* window of the application. Access the *I²C Monitor* by clicking the I²C Monitor icon in the bottom bar, in any of the pages.



Equalizer

The Equalizer window allows the configuration and setting of the different Biquads available in the audio processing of the device. By default, all the equalizers are turned off in the stereo device, while for the mono device, a 120-Hz low pass filter is implemented by default with EQ1.



Figure 6. Equalizer Window

Different equalizer types can be implemented and all the changes to them are reflected in the different plots. Composite plot (red) reflects the sum response of all the equalizers configured. The details of each equalizer setting (as filter type, frequency, gain, and phase) is found in the bottom of the chart section. Each equalizer is turned on or off independently and offer the option of reading or writing the BQ coefficients directly by clicking in the turn (↺) icon. The setting of the equalizers is ganged for left and right channels by default, but can be configured independently by the user when de-selecting “Ganged” box. Phase, Group Delay, Impulse Response, and pole/zero charts are available as well for the analysis of the equalizer response.

Multiband AGL and Full-Band AGL

The TAS5753MD features three multiband AGLs, as well as a full-band AGL. The multiband AGL is used as a three-band crossover, having an independent custom configuration for low, high, and mid frequency bands.

The multiband AGL and full-band AGL also offer the option to use preset configurations based on output power, available for the use of standard power supplies and loads. These presets offer a good starting point towards the full configuration of the end system.

Table 2. Available Presets for Multiband AGL

TAS5753MD Presets
15 W with 12-V PVDD, 4-Ω load
10 W with 12-V PVDD, 4-Ω load
20 W with 24-V PVDD, 8-Ω load
15 W with 24-V PVDD, 8-Ω load
15 W with 19.6-V PVDD, 6-Ω load
10 W with 19.6-V PVDD, 6-Ω load

The filters used for the multiband AGL crossover are configured according to the specific need. By default, the three-band crossover frequencies are set to 300 Hz and 3 kHz, using second-order Linkwitz-Riley filters. This filter type was chosen so the total sum of the three-band signals has a flat response without having to calculate individual cross-over frequencies for unity summation. The crossover frequencies were selected so they are separated far enough in the frequency range from each other to avoid any dip caused by the filter sum response. For the mid-band mixer, the coefficients range is different and features negative values. This is done because when using second order filters to form a band-pass filter; the phase of the signal is inverted, causing an undesired frequency response when summing all the signals. This phase inversion is corrected by using negative coefficients for the mid-band mixer.

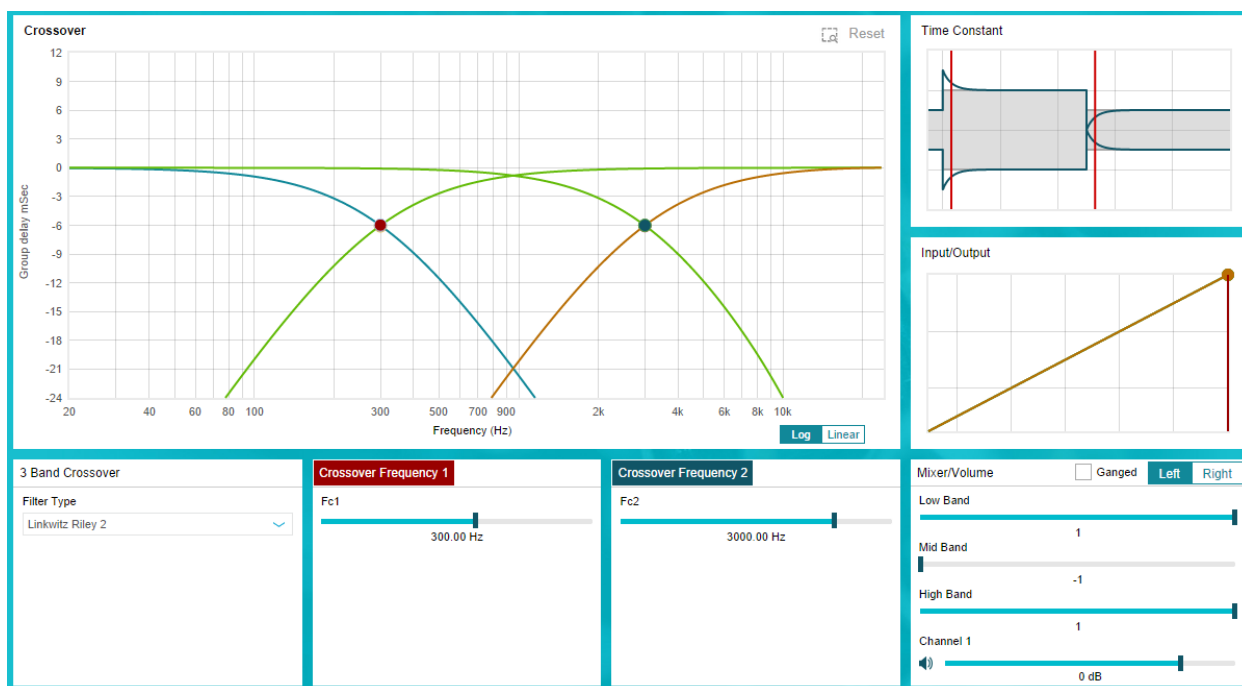
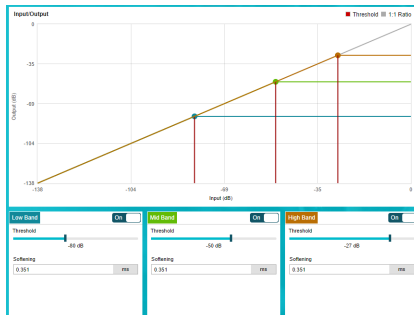
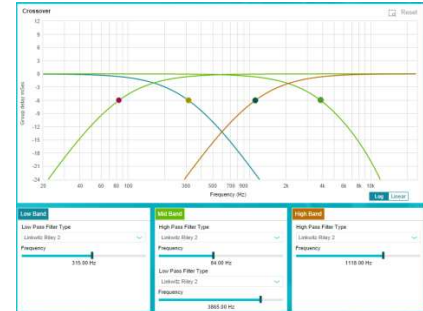


Figure 7. Multiband AGL – Three-Band Crossover

The AGL crossover configuration has two operating modes that can be selected on the top of the main plot:

In basic mode, the crossover frequencies are ganged for left and right channels, and the filters are configured so cutoff frequencies for lowpass, bandpass, and highpass filter are matched.

In advanced mode, the user can modify these parameters individually as well as have a different configuration for left and right channels for the stereo device.



An *Input/Output* chart is available to easily configure the threshold levels for each band. Drag and select each threshold and fine tune the desired threshold level by controlling the levels in the lower part of the window. Modify the *Softening* parameter to configure the sharpness of the compression knee of the AGL.

Attack and release parameters are available for AGL tuning:

Attack Rate: This parameter sets the rate of the attack over the output signal when it is greater than the desired threshold level. This parameter acts fast enough to avoid apparent clipping before engaging.

Release Rate: When the threshold is raised, this parameter reflects the release rate of the compressed signal.



All the multiband AGL functions are also featured in the full-band AGL window. By default, -1 dB is configured for full-band AGL and the attack and release rates are set to 10 V/ms.

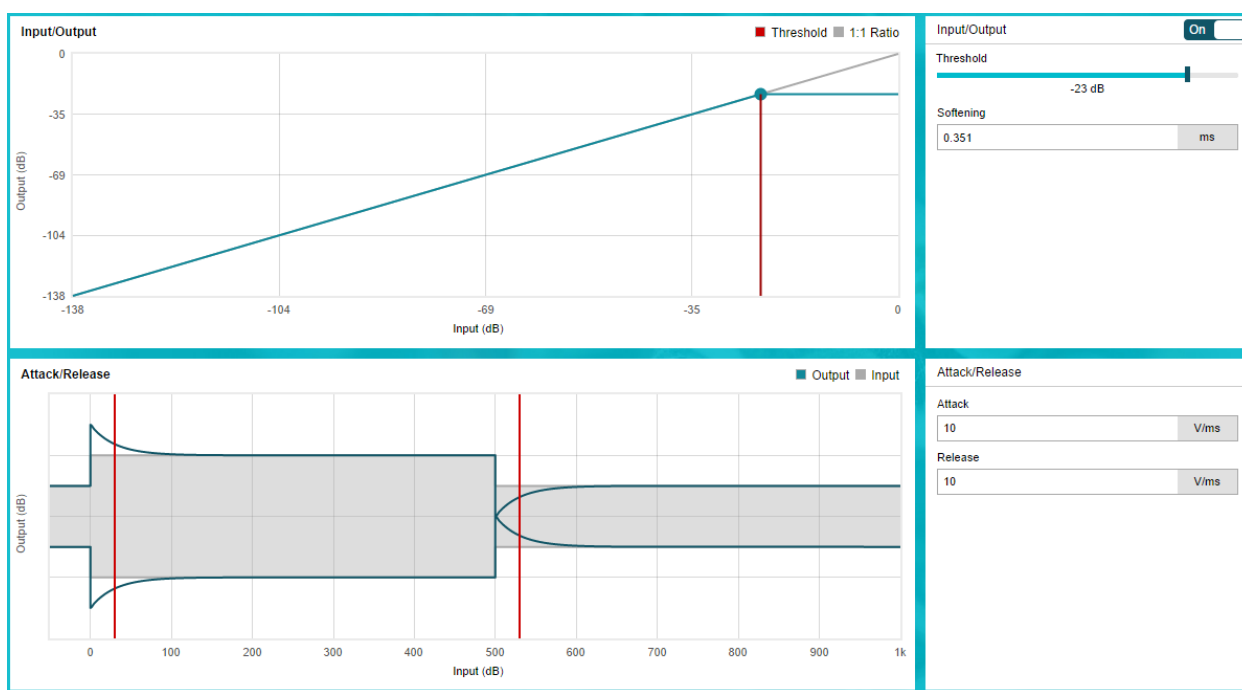


Figure 8. Full-Band AGL

3.6 Register Map

This window is used to monitor and change the main registers of the amplifier.



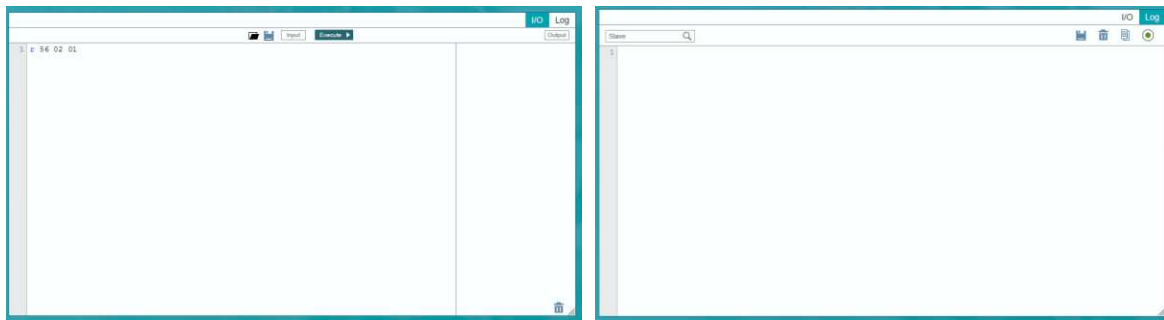
The readings appearing on the registers are related to the selected device, that is, stereo or mono. Manual changes to the register values is accomplished by double-clicking in the desired bit to change. Clicking on *Read All Registers* allows monitoring of the register status of the amplifier. The *Fields* section shows the register name and a brief description of each bit that affects the selected register.

3.7 Direct I²C

This tool manually reads and writes the registers of the amplifier. The *Direct I²C* window is also used to monitor the changes made to the device registers using a logging functionality. The stereo device I²C address of the EVM is 0x56, the mono device I²C address is 0x54.



Direct I²C has two main tabs, I/O and Log, present in the top right corner of the window.



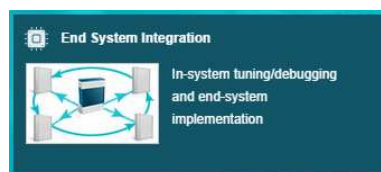
The **I/O** tab in the *I²C Monitor* has two sub sections. The Input section has the provision to enter the read or write commands scripts. Clicking the Execute button executes the commands written in the Input section. The status of the execution is displayed in the *Output* section.

The **Log** tab in the *I²C Monitor* displays the I²C command history, if the record option is enabled. The log tab has different options:

- | | | |
|---|-----------------------------|--|
|  | Search: | search for a particular command |
|  | Save to a file: | saves the log as a .config file to the PC |
|  | Delete Output: | clears the log history |
|  | Copy to a Clipboard: | copies the log text to the clipboard |
|  | Start Recording: | starts recording the I ² C transactions and displays them in the log window |
|  | Stop Recording: | stops recording I ² C transactions |

3.8 End System Integration

The *End System Integration* feature offers a powerful tool to generate a configuration file for use with general processors and a method to debug the device in the end system.



The *End System Integration* window has three main options for the customer (1) *Dump Current State into a Header file*, (2) *In-System Debugging*, and (3) *In-System Tuning*.

What would you like to do?

- ☒ **Dump Current State into a Header File**
Choose this option to download the code to a header file. This generated file will contain the register addresses and the corresponding values that have to be written to the device during boot up.
- ☐ **In-System Debugging**
Choose this option to read or write register values in the end system. Only Register Map and Direct I2C screens will be available.
- ☐ **In-System Tuning**
Choose this option to make fine adjustments in the end system.



Dump Current State into a Header File

This feature allows generation of a configuration file for the evaluated device according to the features evaluated and configured with PPC3. Different options are available for file generation, including the format (.h, .cfg, .mtk), sample rate, device address, and so forth. The generated file is saved in the PC or can be sent to the output window that appears in the window. Take into account that the register configuration is generated from the device that is selected (Mono or Stereo).

Summary

Choose the settings with which to create header/cfg file.

Sample Rate: 48 KHz End System I2C Address: 0x56

Destination: Output Window Dump File: all registers

Format: .h Burst: 1

Dump to Output Window

Output

>

Finish

Use the tuning snapshots feature to save several different operation modes for the device in the end-system. In order to achieve this, first select the desired snapshot, then go to the *End System Integration* window and generate the configuration file.

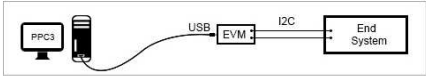
In-System Debugging

This tool helps debug the device when integrated in the end-system. This is possible by connecting the I²C signals of the end-system device to the SCL, SDA, and GND test points of PPCMB. Limited features of the TAS5753MD application are available in this mode. Disconnect from *System Debug Mode* by clicking on the *Disconnect* button on the lower left corner of the window.

In-System Debugging

Choose this option to read or write register values in the end system. Only Register Map and Direct I2C screens will be available.

Stereo Device I2C Address: 0x56 Mono Device I2C Address: 0x54



Connect the End System I2C bus to the SDA, SCL and GND test points on the motherboard.
NOTE: Revision F or newer of PUREPATH-CMDEV allows USB power and removing the Target EVM from the motherboard

In-System Tuning

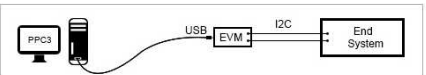
Once the device is integrated in the end application, make fine tuning adjustments to the audio processing with *In-System Tuning*. As with *In-System Debugging*, this is done by connecting I²C signals from PPCMB to the end-system amplifier. Audio processing features are available in this mode, allowing the option to fine tune the AGC, equalizers, and mixing block in the end system.

In-System Tuning

Choose this option to make fine adjustments in the end system.

Sample Rate: 48 KHz

Stereo Device I2C Address: 0x56 Mono Device I2C Address: 0x54



Connect the End System I2C bus to the SDA, SCL and GND test points on the motherboard.
NOTE: Revision F or newer of PUREPATH-CMDEV allows USB power and removing the Target EVM from the motherboard

4 Board Layout, Bill of Materials, and Schematic

This section includes recommendations, the EVM board layouts, bill of materials, and schematics.

The evaluation module has the stereo device populated in the upper section of the board, while the mono device is located on the lower part of the board. A headphone connection is available on the top of the board, it is connected to the output of the headphone/line driver integrated in the stereo device. The connector for the power supply is located between both amplifiers. The connector that interconnects the evaluation module with the PPCMB is located in the left side of the board on the bottom face. The EVM features three connectors at the right side of the board used for the connection of the speakers and loads that are used together with the EVM. These connectors correspond to left and right channel of the stereo device and the single output of the mono device. The board has two standoffs located on each corner of the right side, allowing structural stability when connected to the controller board.



Figure 9. TAS5753MDEV

All the basic components required by the amplifier are located in the top of the board. The output filters are located on the right side of each amplifier, keeping the distance between the inductor and capacitor as short as possible. Each amplifier has a 0.1- μ F decoupling capacitor populated close to the device as well as bulk capacitors close to each PVDD pin connection. The design has wide open areas at the top and bottom part of the amplifier to increase the thermal dissipation of the amplifier.

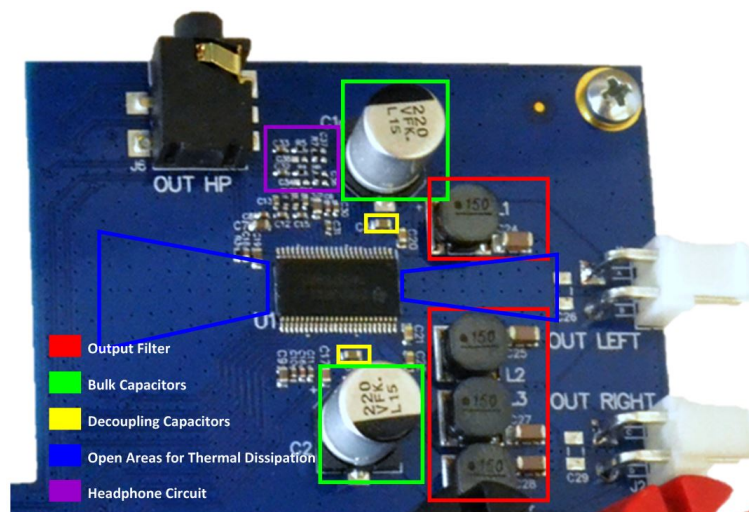


Figure 10. TAS5753MD Layout

The bottom layer of the board is designed to have a clear path that is used as a heat escape from the device. RC-snubber circuits are not generally required in properly-designed 2-layer or 4-layer designs. However, in systems where capacitors for PVDD or LC filter placement is compromised, the snubber circuit is used to slow down the output square waves coming from the IC speaker outputs. A snubber circuit for each output is featured in the evaluation module to showcase their recommended position, if required for an end-system. The circuits are positioned so the thermal flow of the device has a radial clear path out of the board.

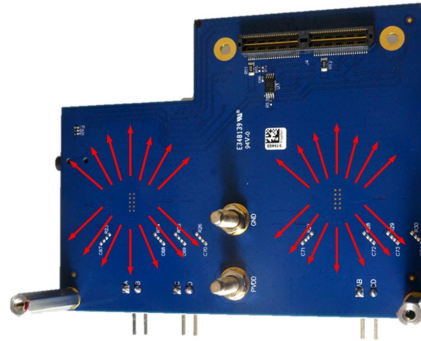


Figure 11. Bottom Layer Thermal Flow

By default, the output filter of the stereo device is configured in BD mode. The user is able to evaluate the devices in AD mode by populating the optional AD capacitors (C26, C29, and C65) in the evaluation module. The I²C address of the devices can be changed as well, if required. By default, the stereo device has an address of 0x56 and the mono device address is 0x54. Resistors R18, R19, R20 and R21 determine the address of each amplifier. Refer to the [schematic](#) of the evaluation module for more information.

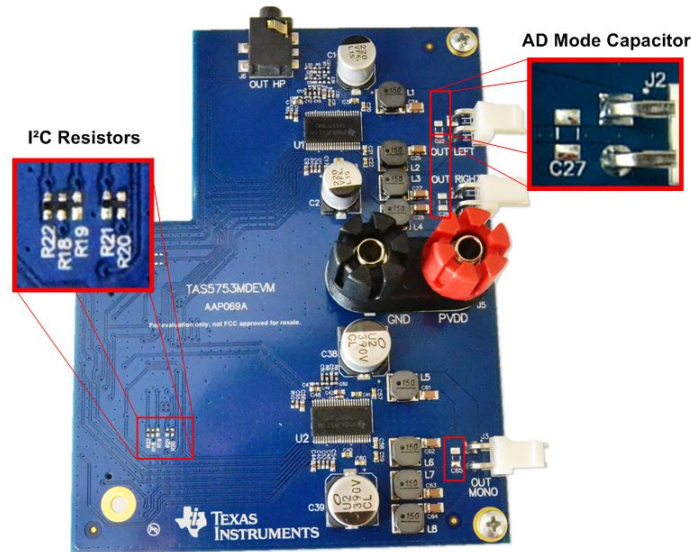


Figure 12. TAS5753MDEVM Optional Features

The evaluation module is a four-layer board designed to enhance the thermal performance and robustness of the design. The second layer is used as ground plane, while the third layer contains the power planes that distribute the supply voltages through the board.

TI recommends following the layout of this EVM as close as possible to get the same performance obtained during the evaluation of the device. Any design variation can be supported by TI through schematic and layout review, as in the case of a different layer number, filter option, and component location, or if performance issues are present in the end-design. Join the [audio amplifier discussion forum](#) at e2e.ti.com for additional design assistance.

4.1 TAS5753MDEVM Board Layout

Figure 13 through Figure 18 show the PCB layouts.

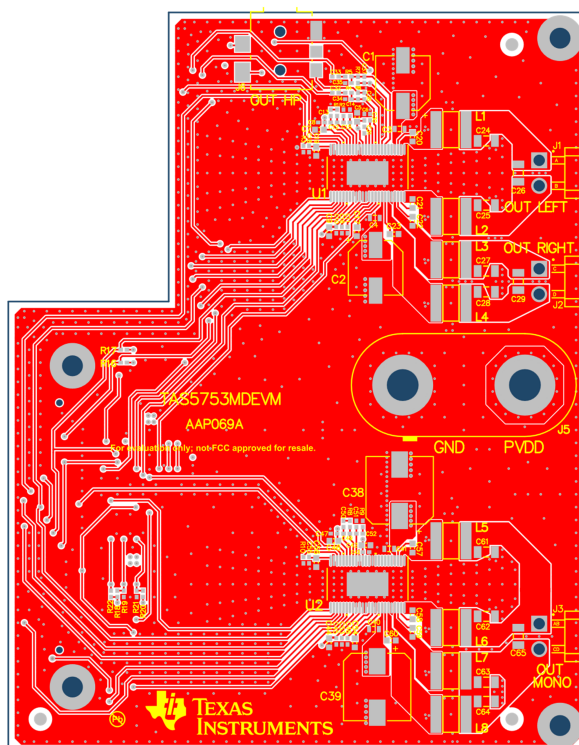


Figure 13. TAS5753MDEVM Top Composite

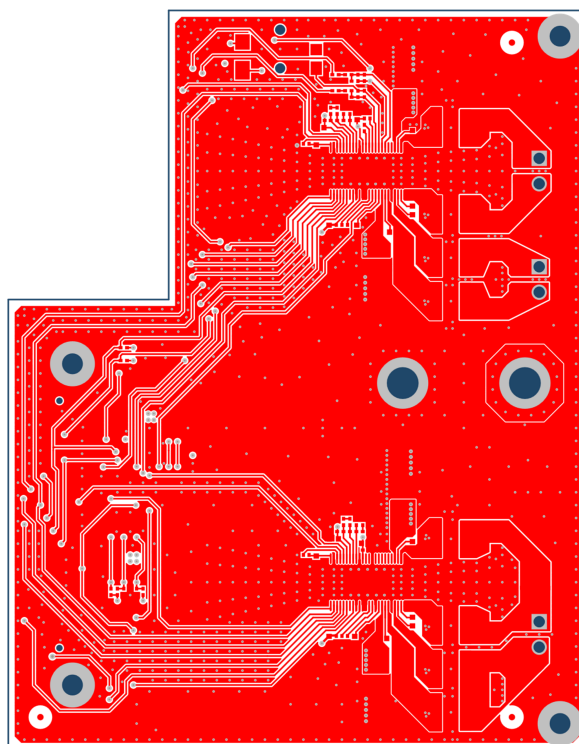


Figure 14. TAS5753MDEVM Top Layer

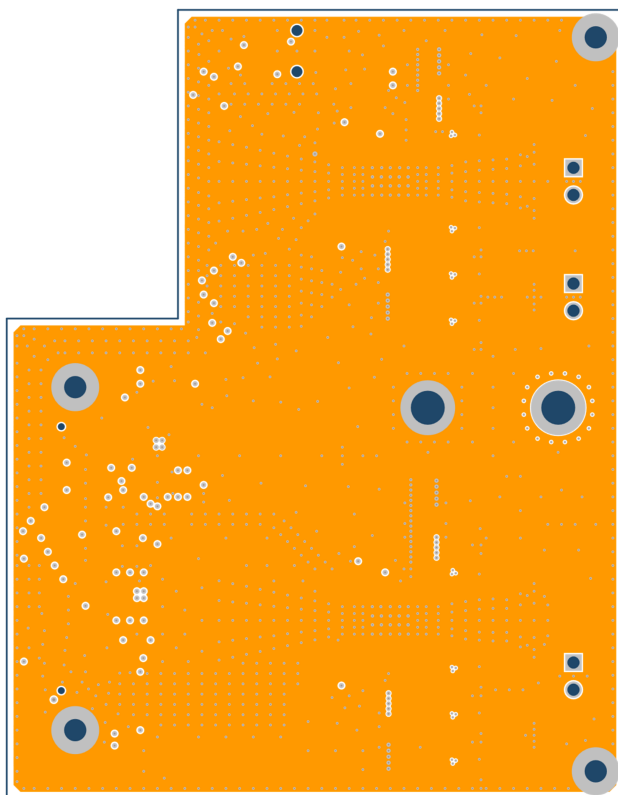


Figure 15. TAS5753MDEVM Ground Layer

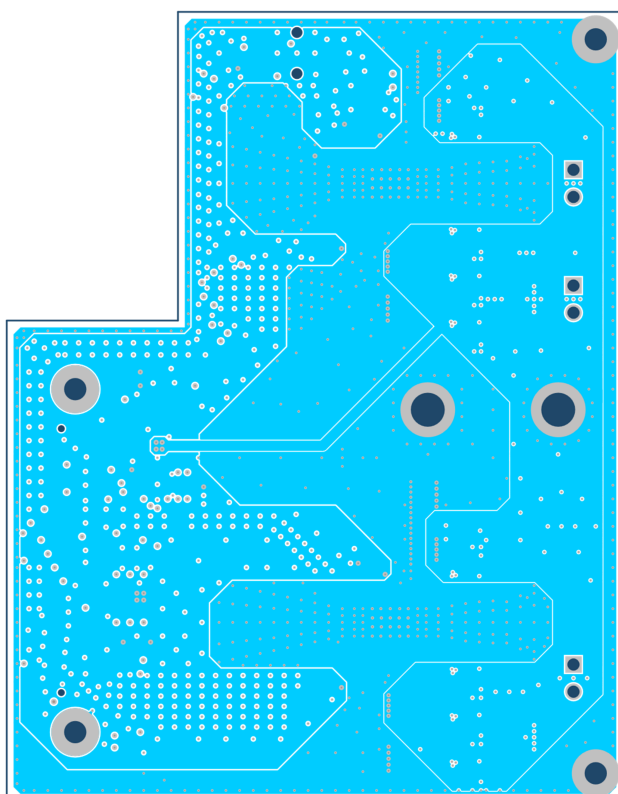


Figure 16. TAS5753MDEVM Power Layer



4.2 Bill of Material

lists the TAS5753MDEVM BOM.

Table 3. TAS5753MDEVM Bill of Materials

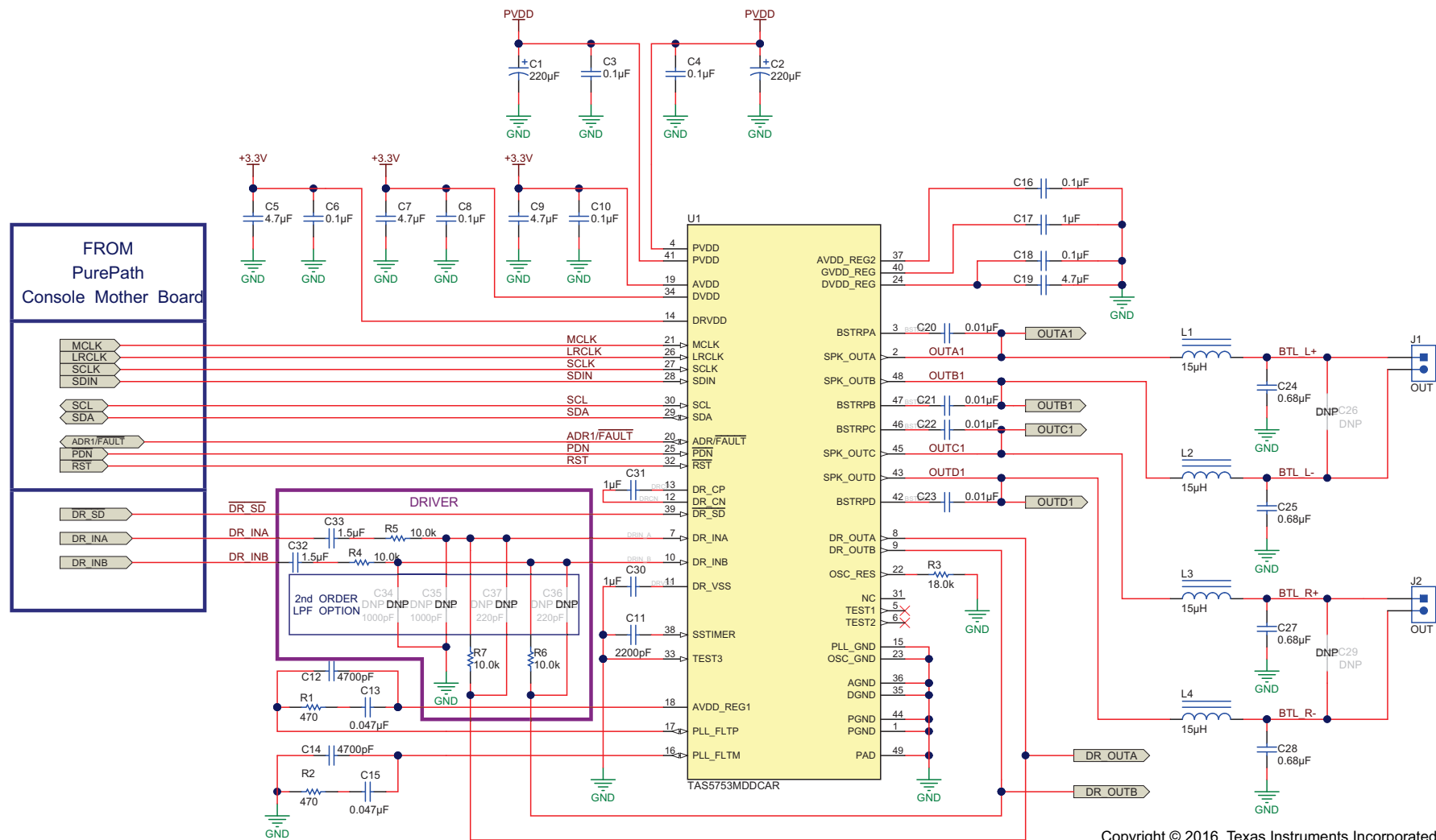
Item #	Designator	Qty	Value	Part Number	Manufacturer	Description	Package Reference
1	!PCB1	1		AAP069	Any	Printed Circuit Board	
2	C1, C2	2	220uF	EEE-FK1V221P	Panasonic	CAP, AL, 220 μ F, 35 V, +/- 20%, 0.16 ohm, SMD	SMT Radial F
3	C3, C4, C40, C41	4	0.1uF	GCM188R71H104KA57D	Murata	CAP, CERM, 0.1 μ F, 50 V, +/- 10%, X7R, 0603	0603
4	C5, C7, C9, C19, C42, C44, C46, C56	8	4.7uF	CGB3B1X5R1A475K055AC	TDK	CAP, CERM, 4.7 μ F, 10 V, +/- 10%, X5R, 0603	0603
5	C6, C8, C10, C16, C18, C43, C45, C47, C53, C55	10	0.1uF	C1005X7R1H104M	TDK	CAP, CERM, 0.1 μ F, 50 V, +/- 20%, X7R, 0402	0402
6	C11, C48	2	2200pF	GRM155R71E222KA01D	Murata	CAP, CERM, 2200 pF, 25 V, +/- 10%, X7R, 0402	0402
7	C12, C14, C49, C51	4	4700pF	GRM155R61H472KA01D	Murata	CAP, CERM, 4700 pF, 50 V, +/- 10%, X5R, 0402	0402
8	C13, C15, C50, C52	4	0.047uF	GRM155R71C473KA01D	Murata	CAP, CERM, 0.047 μ F, 16 V, +/- 10%, X7R, 0402	0402
9	C17, C54	2	1uF	GRM188R71E105KA12D	Murata	CAP, CERM, 1 μ F, 25 V, +/- 10%, X7R, 0603	0603
10	C20, C21, C22, C23, C57, C58, C59, C60	8	0.01uF	GRM188R71H103KA01D	Murata	CAP, CERM, 0.01 μ F, 50 V, +/- 10%, X7R, 0603	0603
11	C24, C25, C27, C28, C61, C62, C63, C64	8	0.68uF	GRM31MR71H684KA88L	Murata	CAP, CERM, 0.68 μ F, 50 V, +/- 10%, X7R, 1206	1206
12	C30, C31, C75	3	1uF	C1005X5R1A105K050BB	TDK	CAP, CERM, 1 μ F, 10 V, +/- 10%, X5R, 0402	0402
13	C32, C33	2	1.5uF	C1005X5R1A155K050BC	TDK	CAP, CERM, 1.5 μ F, 10 V, +/- 10%, X5R, 0402	0402
14	C38, C39	2	390uF	UCL1V391MNL1GS	Nichicon	CAP, AL, 390 μ F, 35 V, +/- 20%, 0.08 ohm, SMD	10x10
15	C66	1	0.1uF	C1005X7R1H104K050BB	TDK	CAP, CERM, 0.1uF, 50V, +/-10%, X7R, 0402	0402
16	H1, H2	2		MPMS 003 0005 PH	B&F Fastener Supply	MACHINE SCREW PAN PHILLIPS M3 5mm	Screw M3 Phillips head
17	H3, H4	2		R30-1003002	Harwin	Standoff, HexBrass M3, 30 mm	Spacer M3, 30mm
18	J1, J2, J3	3		B2PS-VH(LF)(SN)	JST Manufacturing	Header (friction lock), 3.96mm, 2x1, Tin, R/A, TH	Header, 2x1, 3.96mm, R/A
19	J4	1		QTS-050-01-F-D-A	Samtec	Connector, 100 Pos. 0.635mm, SMT	Connector, 1575x235x280 mil
20	J5	1		6883	Pomona Electronics	Dual Binding Posts with Base, 2x1, TH	Dual Binding Posts with Base, 2x1, TH
21	J6	1		SJ1-3514-SMT-TR	CUI Inc.	Audio Jack, 3.5mm, Stereo, R/A, Black, SMT	Audio Jack, 15x5x9.5mm SMT
22	L1, L2, L3, L4, L5, L6, L7, L8	8	15uH	1255AY-150M=P3	Murata Toko	Inductor, Shielded, 15 μ H, 3 A, 0.063 ohm, SMD	6.3x4.5x6.3mm
23	R1, R2, R8, R9	4	470	ERJ-2RKf4700X	Panasonic	RES, 470, 1%, 0.1 W, 0402	0402
24	R3, R10	2	18.0k	CRCW040218K0FKED	Vishay-Dale	RES, 18.0 k, 1%, 0.063 W, 0402	0402
25	R4, R5, R6, R7, R13, R15, R31, R32	8	10.0k	CRCW040210K0FKED	Vishay-Dale	RES, 10.0 k, 1%, 0.063 W, 0402	0402
26	R11, R12	2	0	CRCW12060000Z0EA	Vishay-Dale	RES, 0, 5%, 0.25 W, 1206	1206
27	R18, R21, R22	3	47k	CRCW040247K0JNED	Vishay-Dale	RES, 47 k, 5%, 0.063 W, 0402	0402
28	U1, U2	2		TAS5753MDDCAR	Texas Instruments	Digital Audio Power Amplifier with EQ, AGL and Headphone/Line Driver , DCA0048B	DCA0048B

Table 3. TAS5753MDEVM Bill of Materials (continued)

Item #	Designator	Qty	Value	Part Number	Manufacturer	Description	Package Reference
29	U3	1		24LC512-I/ST	Microchip	EEPROM, 512KBIT, 400KHZ, 8TSSOP	TSSOP-8
30	C26, C29, C65	0	0.33uF	GRM319R71H334KA01D	Murata	CAP, CERM, 0.33 μ F, 50 V, +/- 10%, X7R, 1206	1206
31	C34, C35	0	1000pF	GRM1555C1H102JA01D	Murata	CAP, CERM, 1000 pF, 50 V, +/- 5%, C0G/NP0, 0402	0402
32	C36, C37	0	220pF	GRM1555C1H221JA01D	Murata	CAP, CERM, 220 pF, 50 V, +/- 5%, C0G/NP0, 0402	0402
33	C67, C68, C69, C70, C71, C72, C73, C74	0	330pF	GRM1885C1H331JA01D	Murata	CAP, CERM, 330 pF, 50 V, +/- 5%, C0G/NP0, 0603	0603
34	FID1, FID2, FID3, FID4, FID5, FID6	0		N/A	N/A	Fiducial mark. There is nothing to buy or mount.	Fiducial
35	R14	0	10.0k	CRCW040210K0FKED	Vishay-Dale	RES, 10.0 k, 1%, 0.063 W, 0402	0402
36	R16, R17	0	2.00k	CRCW04022K00FKED	Vishay-Dale	RES, 2.00 k, 1%, 0.063 W, 0402	0402
37	R19, R20	0	47k	CRCW040247K0JNED	Vishay-Dale	RES, 47 k, 5%, 0.063 W, 0402	0402
38	R23, R24, R25, R26, R27, R28, R29, R30	0	18	CRCW060318R0JNEA	Vishay-Dale	RES, 18, 5%, 0.1 W, 0603	0603

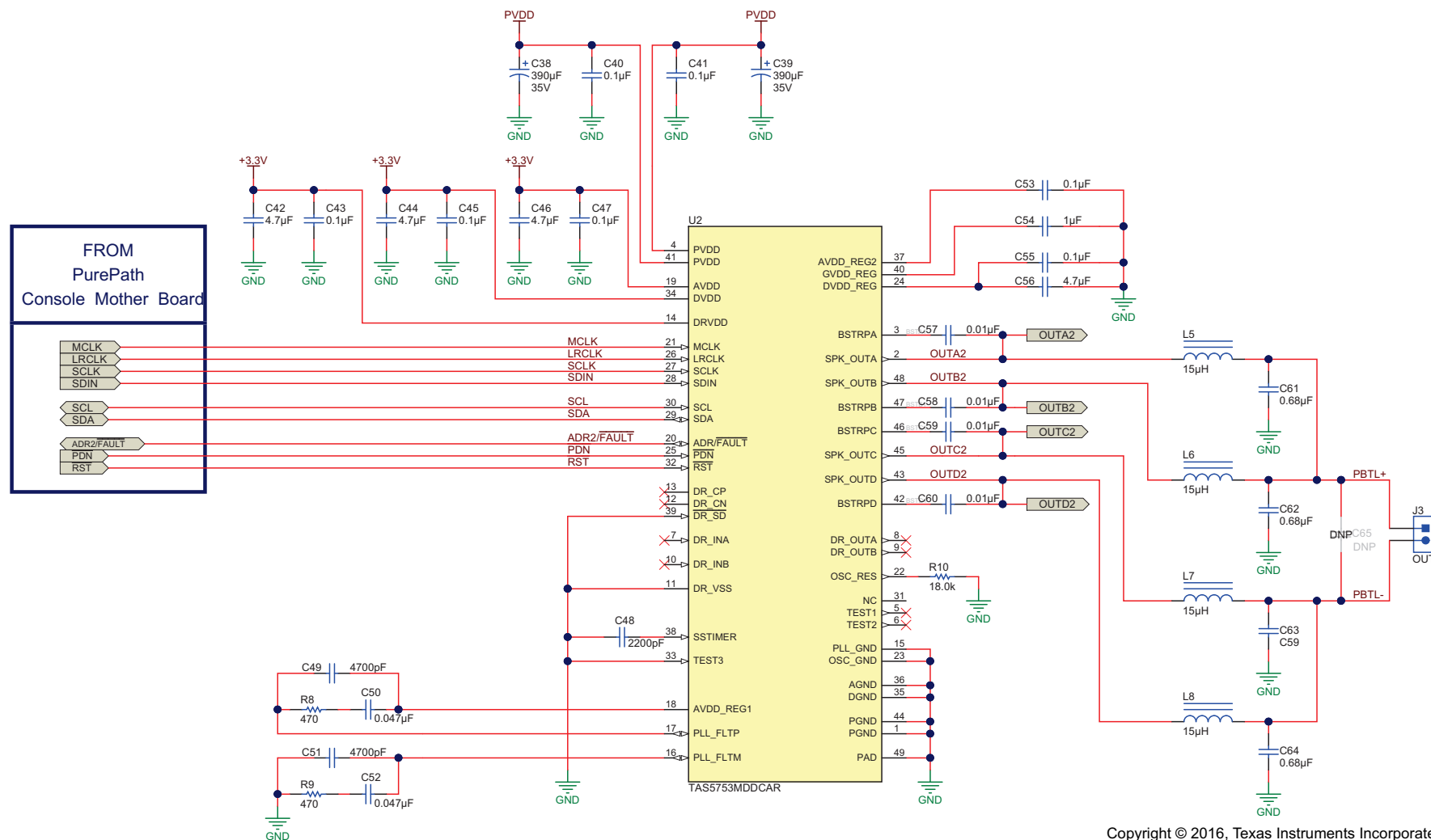
4.3 Schematic

Figure 19 through Figure 21 show the TAS5753MDEV schematic.



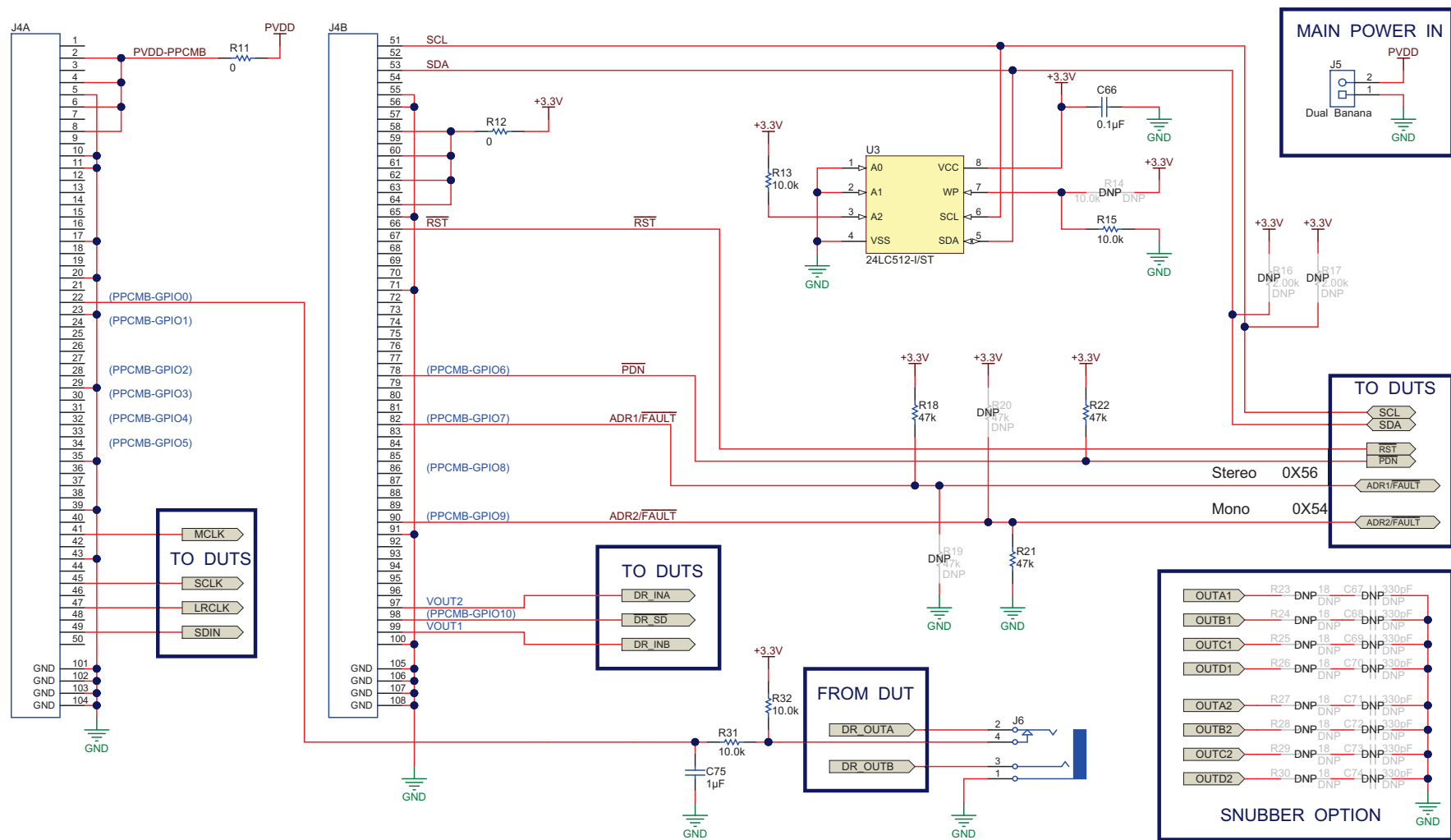
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Figure 19. TAS5753MDEV Stereo Device



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Figure 20. TAS5753MDEV Mono Device



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Figure 21. TAS5753MDEVM PPCMB and Power Supply Connection

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CAUTION

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- *Reorient or relocate the receiving antenna.*
- *Increase the separation between the equipment and receiver.*
- *Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.*
- *Consult the dealer or an experienced radio/TV technician for help.*

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Concernant les EVMs avec antennes détachables

Conformément à la réglementation d'Industrie Canada, le présent émetteur radio peut fonctionner avec une antenne d'un type et d'un gain maximal (ou inférieur) approuvé pour l'émetteur par Industrie Canada. Dans le but de réduire les risques de brouillage radioélectrique à l'intention des autres utilisateurs, il faut choisir le type d'antenne et son gain de sorte que la puissance isotrope rayonnée équivalente (p.i.r.e.) ne dépasse pas l'intensité nécessaire à l'établissement d'une communication satisfaisante. Le présent émetteur radio a été approuvé par Industrie Canada pour fonctionner avec les types d'antenne énumérés dans le manuel d'usage et ayant un gain admissible maximal et l'impédance requise pour chaque type d'antenne. Les types d'antenne non inclus dans cette liste, ou dont le gain est supérieur au gain maximal indiqué, sont strictement interdits pour l'exploitation de l'émetteur.

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http://www.tij.co.jp/llds/ti_ja/general/eStore/notice_01.page

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Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

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